



Additive Manufacturing and System: From Methods to Applications

Guest Editors:

Prof. Dr. Namhun Kim

The School of Mechanical,
Aerospace, and Nuclear
Engineering, Ulsan National
Institute of Science and
Technology, Ulsan 44919, Korea

Prof. Dr. Seung Ki Moon

School of Mechanical and
Aerospace Engineering, Nanyang
Technological University, 50
Nanyang Ave, Singapore 639798,
Singapore

Prof. Dr. Rohan Shirwaiker

Edward P. Fitts Department of
Industrial and Systems
Engineering, North Carolina State
University, Raleigh, NC 27695,
USA

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Message from the Guest Editors

Dear Colleagues,

Additive manufacturing (AM or 3D printing) has been regarded as integral to the future manufacturing technologies of the fourth industrial revolution. Its limitless capability for incorporating complexities in design, processes, materials, and functionalities is gaining huge attention from both research and industry sectors. The successful implementation and application of AM technologies in real systems requires that the breadth and depth of knowledge span the whole process of integrating and realizing a system, or a part, from design to production (and even to validation, maintenance, and quality assurance). The seamless combination of the design, simulation, process planning, and production for AM is essential from the perspective of implementing effective and efficient manufacturing systems.

In this Special Issue, we aim to cover additive manufacturing technology from method to application, especially in the fields of automotive, aerospace, and biomedical engineering, and sharing insights toward the industrial implementation of AM technology.

Prof. Namhun Kim
Prof. Seung Ki Moon
Prof. Rohan Shirwaiker
Guest Editors





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Editor-in-Chief

Prof. Dr. Giulio Nicola Cerullo
Dipartimento di Fisica,
Politecnico di Milano, Piazza L.
da Vinci 32, 20133 Milano, Italy

Message from the Editor-in-Chief

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Applied Sciences Editorial Office
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